

Title (en)
COMPOSITE MATERIAL, ESPECIALLY MULTILAYER MATERIAL, AND ADHESIVE OR BONDING MATERIAL

Title (de)
VERBUNDMATERIAL, INSBESONDERE MEHRSCHICHTMATERIAL SOWIE KLEBER- ODER BONDMATERIAL

Title (fr)
MATERIAU COMPOSITE, EN PARTICULIER MATERIAU MULTICOUCHE, AINSI QUE MATERIAU ADHESIF ET MATERIAU DE LIAISON

Publication
EP 1963455 A1 20080903 (DE)

Application
EP 06820829 A 20060810

Priority

- IB 2006003030 W 20060810
- DE 102005062181 A 20051223

Abstract (en)
[origin: WO2007072126A1] Disclosed is a multilayer material in which at least two components are joined to each other via an adhesive bond. Said adhesive bond is formed by an adhesive or bonding layer containing nanofiber material in a matrix that is suitable as an adhesive.

IPC 8 full level
C09J 163/00 (2006.01); **B32B 7/12** (2006.01); **B32B 27/20** (2006.01)

CPC (source: EP US)
B32B 7/12 (2013.01 - EP US); **B32B 9/005** (2013.01 - EP US); **B32B 9/041** (2013.01 - EP US); **B32B 15/20** (2013.01 - EP US); **B32B 27/20** (2013.01 - EP US); **B32B 27/36** (2013.01 - EP US); **B32B 27/38** (2013.01 - EP US); **B82Y 10/00** (2013.01 - EP US); **B82Y 30/00** (2013.01 - EP US); **C09J 11/00** (2013.01 - EP US); **C09J 163/00** (2013.01 - EP US); **H01L 23/373** (2013.01 - EP US); **H01L 23/3735** (2013.01 - EP US); **H05K 3/386** (2013.01 - EP US); **B32B 2250/40** (2013.01 - EP US); **B32B 2255/26** (2013.01 - EP US); **B32B 2262/02** (2013.01 - EP US); **B32B 2262/106** (2013.01 - EP US); **B32B 2264/102** (2013.01 - EP US); **B32B 2307/208** (2013.01 - EP US); **B32B 2307/302** (2013.01 - EP US); **C08K 7/02** (2013.01 - EP US); **C08K 2201/011** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H05K 1/0306** (2013.01 - EP US); **H05K 2201/0251** (2013.01 - EP US); **H05K 2201/026** (2013.01 - EP US); **H05K 2201/0323** (2013.01 - EP US); **H05K 2201/0355** (2013.01 - EP US); **H05K 2201/083** (2013.01 - EP US); **H05K 2203/104** (2013.01 - EP US); **Y10T 428/24** (2015.01 - EP US); **Y10T 428/24058** (2015.01 - EP US); **Y10T 428/24132** (2015.01 - EP US); **Y10T 428/249942** (2015.04 - EP US); **Y10T 428/31515** (2015.04 - EP US)

C-Set (source: EP US)
H01L 2924/0002 + H01L 2924/00

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DOCDB simple family (publication)
WO 2007072126 A1 20070628; CN 101341225 A 20090107; CN 101341225 B 20130515; DE 102005062181 A1 20070705; DE 102005063403 A1 20070906; EP 1963455 A1 20080903; JP 2009520612 A 20090528; JP 5343283 B2 20131113; US 2010227114 A1 20100909; US 2012031653 A1 20120209; US 8119220 B2 20120221; US 8304054 B2 20121106

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